

Special Issue

Image Sensors and Companion Chips

Message from the Guest Editor

CMOS image sensors are highly integrated optoelectronic chips which convert optical information into digital information that is easy to process and store. With the development of 3D integration and packaging technology, multiple chips can be integrated into one chip to form more compact imaging systems. This Special Issue encourages researchers to present their theories, techniques, circuits, and systems of CMOS chips for image sensing and companion chips. The scope of this Special Issue focuses on, but is not limited to:

- CMOS image sensor modeling;
- High-performance active pixels;
- Low-noise readout circuits;
- High-speed imaging techniques;
- Dynamic range extension technology;
- Low-light imaging;
- High-resolution imaging;
- 3D imaging;
- Dynamic vision sensors;
- Spike-based image sensors;
- Sensory and computational integration;
- Image signal processing;
- Single photon counting technique;
- Image sensor interfaces.

Guest Editor

Dr. Kaiming Nie

School of Microelectronics, Tianjin University, Tianjin 300072, China

Deadline for manuscript submissions

closed (20 August 2024)



Electronics

an Open Access Journal
by MDPI

Impact Factor 2.6
CiteScore 6.1



mdpi.com/si/190247

Electronics
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
electronics@mdpi.com

[mdpi.com/journal/
electronics](https://mdpi.com/journal/electronics)





Electronics

an Open Access Journal
by MDPI

Impact Factor 2.6
CiteScore 6.1



[mdpi.com/journal/
electronics](https://mdpi.com/journal/electronics)



About the Journal

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

Editor-in-Chief

Prof. Dr. Flavio Canavero

Department of Electronics and Telecommunications, Politecnico di
Torino, 10129 Torino, Italy

Author Benefits

High Visibility:

indexed within Scopus, SCIE (Web of Science), CAPus /
SciFinder, Inspec, Ei Compendex and other databases.

Journal Rank:

JCR - Q2 (Engineering, Electrical and Electronic) /
CiteScore - Q1 (Electrical and Electronic Engineering)

Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 16.8 days after submission; acceptance to publication is undertaken in 2.4 days (median values for papers published in this journal in the first half of 2025).